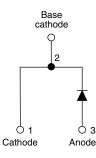
VS-HFA25PB60-N3

Vishay Semiconductors

HEXFRED[®] Ultrafast Soft Recovery Diode, 25 A



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PRIMARY CHARACTERISTICS								
I _{F(AV)}	25 A							
V _R	600 V							
V _F at I _F	1.3 V							
t _{rr} (yp.	23 ns							
T _J max.	150 °C							
Package	TO-247AC 2L							
Circuit configuration	Single							

FEATURES

- Ultrafast and ultrasoft recovery
- Very low I_{RRM} and Q_{rr}
- Designed and qualified according to JEDEC[®]-JESD 47
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

BENEFITS

- Reduced RFI and EMI
- · Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

DESCRIPTION

VS-HFA25PB60... is a state of the art ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 25 A continuous current, the VS-HFA25PB60... is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{BBM}) and does not exhibit any tendency to "snap-off" during the t_b portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA25PB60... is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS					
Cathode to anode voltage	V _R		600	V					
Maximum continuous forward current	١ _F	T _C = 100 °C	25						
Single pulse forward current	I _{FSM}	t _p = 10 ms	225	А					
Maximum repetitive forward current	I _{FRM}		100						
Movimum power discipation	Р	T _C = 25 °C	151	W					
Maximum power dissipation	P _D	T _C = 100 °C	60	vv					
Operating junction and storage temperature range	T _J , T _{Stg}		-55 to +150	°C					

RoHS COMPLIANT HALOGEN

Revision: 19-Sep-2019

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ELECTRICAL SPECIFICATIONS ($T_J = 25 \ ^{\circ}C$ unless otherwise specified)								
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS	
Cathode to anode breakdown voltage	V _{BR}	I _R = 100 μA		600	-	-		
		I _F = 25 A		-	1.3	1.7	V	
Maximum forward voltage	V _{FM}	I _F = 50 A	See fig. 1	-	1.5	2.0		
		I _F = 25 A, T _J = 125 °C		-	1.3	1.7		
Maximum reverse		$V_R = V_R$ rated	See fig. 2	-	1.5	20		
leakage current	I _{RM}	T_J = 125 °C, V_R = 0.8 x V_R rated	See lig. 2	-	600	2000	μΑ	
Junction capacitance	CT	V _R = 200 V	See fig. 3	-	55	100	pF	
Series inductance	L _S	Measured lead to lead 5 mm from p	ackage body	-	12	-	nH	

DYNAMIC RECOVERY CHARACTERISTICS ($T_J = 25$ °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS		
Reverse recovery time See fig. 5, 10	t _{rr}	$I_F = 1.0 \text{ A}, \text{ d}I_F/\text{d}t = 200$	-	23	-				
	t _{rr1}	T _J = 25 °C		-	50	75	ns		
	t _{rr2}	T _J = 125 °C	I _F = 25 A dI _F /dt = 200 A/μs V _R = 200 V	-	105	160			
Peak recovery current See fig. 6, 10	I _{RRM1}	T _J = 25 °C		-	4.5	10	A nC A/us		
	I _{RRM2}	T _J = 125 °C		-	8.0	15			
Reverse recovery charge	Q _{rr1}	T _J = 25 °C		-	112	375			
See fig. 7, 10	Q _{rr2}	T _J = 125 °C		-	420	1200			
Peak rate of fall of recovery current during t _b	dl _{(rec)M} /dt1	T _J = 25 °C		-	250	-			
See fig. 8, 10	dl _{(rec)M} /dt2	T _J = 125 °C		-	160	-	Ανμδ		

THERMAL - MECHANICAL SPECIFICATIONS										
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS				
Lead temperature	T _{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	°C				
Thermal resistance, junction to case	R _{thJC}		-	-	0.83					
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	-	-	40	K/W				
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	0.25	-					
Weight			-	6.0	-	g				
weight			-	0.21	-	oz.				
Mounting torque			6.0 (5.0)	-	12 (10)	kgf ·cm (lbf ·in)				
Marking device		Case style TO-247AC 2L		HFA25PB60						

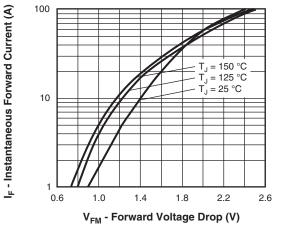
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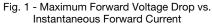
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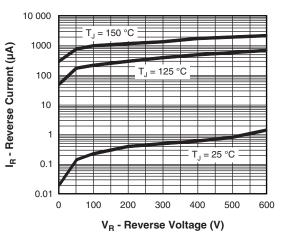


Fig. 2 - Typical Reverse Current vs. Reverse Voltage

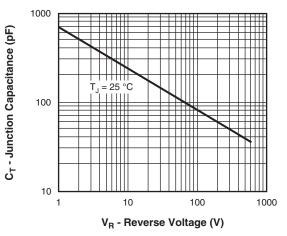
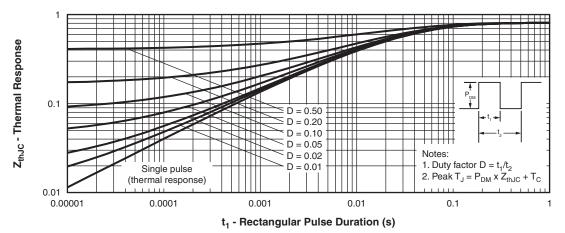


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage





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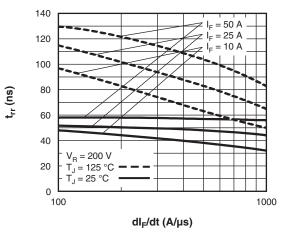


Fig. 5 - Typical Reverse Recovery Time vs. dl_F/dt

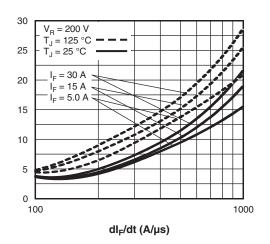
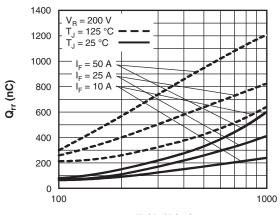


Fig. 6 - Typical Recovery Current vs. dI_F/dt



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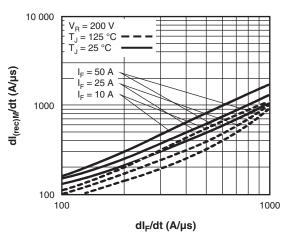


Fig. 8 - Typical $dI_{(rec)M}/dt$ vs. dI_F/dt

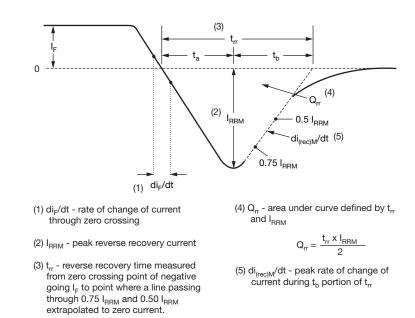


Fig. 9 - Reverse Recovery Waveform and Definitions

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I_{RR} (A)



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ORDERING INFORMATION TABLE

Device code	VS-	HF	Α	25	РВ	60	-N3	
	1	2	3	4	5	6	7	
	Vishay Semiconductors product							
	 2 - HEXFRED[®] family 3 - Electron irradiated 							

Current rating (25 = 25 A)

- PB = TO-247AC, 2 pins
- 5 6 Voltage rating: (60 = 600 V) -
- 7 Environmental digit: _

4

-N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

ORDERING INFORMATION (Example)									
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION						
VS-HFA25PB60-N3	25	500	Antistatic plastic tube						

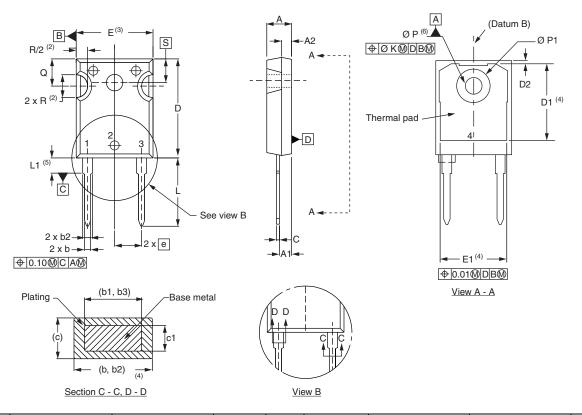
LINKS TO RELATED DOCUMENTS							
Dimensions	www.vishay.com/doc?96144						
Part marking information	www.vishay.com/doc?95648						
SPICE model	www.vishay.com/doc?96665						



Vishay Semiconductors

TO-247AC 2L

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INC	HES	NOTES	NOTES		MILLIN	IETERS	INC	HES	NOTES
STIVIDOL	MIN.	MAX.	MIN.	MAX.	NOTES		SYMBOL	MIN.	MAX.	MIN.	MAX.	NOTES
A	4.65	5.31	0.183	0.209			E	15.29	15.87	0.602	0.625	3
A1	2.21	2.59	0.087	0.102			E1	13.46	-	0.53	-	
A2	1.17	1.37	0.046	0.054			e	5.46	BSC	0.215	BSC	
b	0.99	1.40	0.039	0.055			ØК	0.2	254	0.0)10	
b1	0.99	1.35	0.039	0.053			L	14.20	16.10	0.559	0.634	
b2	1.65	2.39	0.065	0.094			L1	3.71	4.29	0.146	0.169	
b3	1.65	2.34	0.065	0.092			ØР	3.56	3.66	0.14	0.144	
с	0.38	0.89	0.015	0.035			Ø P1	-	7.39	-	0.291	
c1	0.38	0.84	0.015	0.033			Q	5.31	5.69	0.209	0.224	
D	19.71	20.70	0.776	0.815	3		R	4.52	5.49	0.178	0.216	
D1	13.08	-	0.515	-	4		S	5.51	BSC	0.217	BSC	
D2	0.51	1.35	0.020	0.053								
NI - I												

Notes

⁽¹⁾ Dimensioning and tolerancing per ASME Y14.5M-1994

(2) Contour of slot optional

(3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body

⁽⁴⁾ Thermal pad contour optional with dimensions D1 and E1

⁽⁵⁾ Lead finish uncontrolled in L1

(6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")

⁽⁷⁾ Outline conforms to JEDEC[®] outline TO-247 with exception of dimension Q

Revision: 07-Dec-17

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